Press Release

ECTC is 1 MONTH AWAY!
VISIT YINCAE BOOTH # 506
May 31st to June 3rd

(Albany, NY) 4/27/2016 – ECTC is only 1 month away! The tradeshow will take place at The Cosmopolitan hotel in Las Vegas, NV from May 31st to June 3rd. YINCAE hopes that you will stop by our Booth 506 to learn more about YINCAE and the innovative products we have to offer.

YINCAE offers a variety of exclusive Adhesives, Thermal Interface, and Chip/Board/Packaging level materials that have been adopted by leading contract manufacturers and Tier 1 Microelectronic suppliers. YINCAE innovated the WORLD's FIRST Lead-Free Solder Joint Encapsulation Adhesive solutions for wafer level, flip chip, POP, LGA, BGA and many more applications. YINCAE offers SJEA for low, medium, and high temperature solder alloy applications for your individualized needs.

YINCAE Advanced Materials, LLC hopes that you will join us at the conference to learn about YINCAE and the solutions that we have to offer. We have exclusive products that no other company has developed. YINCAE hopes to see you there at the conference. Please visit us at booth 506!

If you wish to visit the official website of YINCAE Advanced Materials, LLC, please visit us by clicking the following link: YINCAE Website.

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Founded in 2005 & headquartered in Albany, New York, YINCAE Advanced Materials is a leading manufacturer and supplier of high-performance coatings, adhesives and electronic materials used in the microchip & optoelectronic devices. YINCAE products provide new technologies to support manufacturing processes from wafer level, to package level, to board level and final devices while facilitating smarter and faster production and supporting green initiatives.

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